

**FEATURES/BENEFITS**

- JEDEC compatible LVTTTL level
- 10 low skew clock outputs
- Monitor output
- Clock inputs are 5V tolerant
- Pinout and function compatible with QS5806
- QS532806 has 25Ω on-chip resistors for low noise
- Input hysteresis for better noise margin
- Guaranteed low skew
  - 0.3ns same bank
  - 0.6ns opposite transition
  - 1.0ns different devices
- Industrial temperature range
- Available in QSOP (Q) and SOIC (SO)

**DESCRIPTION**

The QS53806 and QS532806 clock driver/buffer circuits can be used for clock buffering schemes where low skew is a key parameter. The QS53806 offers two banks of five inverting outputs. Designed in QSI's proprietary QCMOS process, these devices provide low propagation delay buffering with on-chip skew of 0.3ns for same-transition, same-bank signals.

The QS532806 has on-chip series termination resistors for lower noise clock signals. The series resistor versions are recommended for driving unterminated lines with capacitive loading and other noise sensitive clock distribution circuits. These clock buffer products are designed for use in high-performance workstations, embedded and personal computing systems. Several devices can be used in parallel or scattered throughout a system for guaranteed low skew, system-wide clock distribution networks.

See Application Note AN-21A for more information on low-skew clock buffers.

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**Figure 1. Functional Block Diagram**

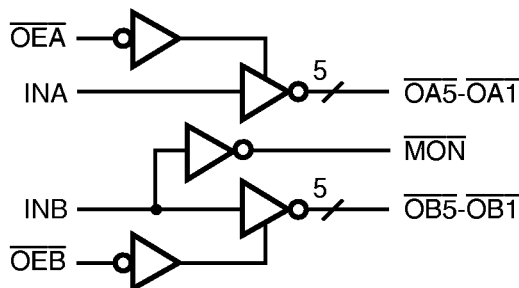


Figure 2. Pin Configurations (All Pins Top View)

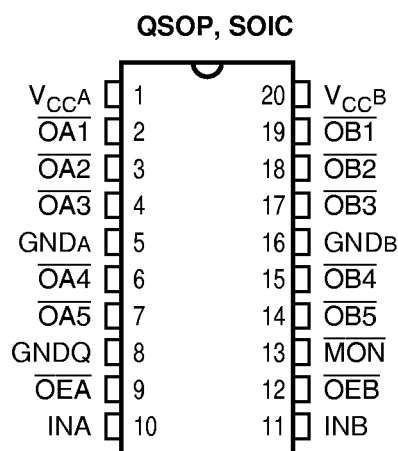


Table 1. Pin Description

Name	I/O	Function
$\overline{OEA}$ , $\overline{OEB}$	I	Output Enable Inputs
INA, INB	I	Clock Inputs
$\overline{OAn}$ , $\overline{OBn}$	O	Clock Outputs
$\overline{MON}$	O	Monitor Outputs (non-disable)

Table 2. Absolute Maximum Ratings

Supply Voltage to Ground .....	-0.5V to +7.0V
DC Output Voltage $V_{OUT}$ .....	-0.5V to +7.0V
DC Input Voltage $V_{IN}$ .....	-0.5V to +7.0V
AC Input Voltage (for a pulse width $\leq 20$ ns) .....	-3.0V
DC Input Diode Current with $V_{IN} < 0$ .....	-20mA
DC Output Current Max. Sink Current/Pin .....	120mA
Maximum Power Dissipation At $T_A = 85^\circ\text{C}$ , QSOP .....	0.82 watts
SOIC .....	0.75 watts
$T_{STG}$ Storage Temperature .....	-65° to +150°C

**Note:** Stresses greater than those listed under absolute maximum ratings may cause permanent damage to QSI devices that result in functional or reliability type failures.

Table 3. Capacitance

$T_A = 25^\circ\text{C}$ ,  $f = 1\text{MHz}$ ,  $V_{IN} = 0\text{V}$

Pins	QSOP		SOIC		Unit
	Typ	Max	Typ	Max	
All Pins	4	6	5	7	pF

**Note:** Capacitance is characterized but not tested.

**Table 4. DC Electrical Characteristics Over Operating Range**

Industrial:  $T_A = -40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ ,  $V_{CC} = 3.3 \pm 0.3\text{V}$

Symbol	Parameter	Test Conditions	Min	Typ <sup>(1)</sup>	Max	Unit
$V_{IH}$	Input HIGH Voltage	Guaranteed Logic HIGH for Inputs	2.0	—	5.5	V
$V_{IL}$	Input LOW Voltage	Guaranteed Logic LOW for Inputs	-0.5	—	0.8	
$V_{IC}$	Clamp Diode Voltage <sup>(3)</sup>	$V_{CC} = \text{Min.}, I_{IN} = -18\text{mA}$	—	-0.7	-1.2	
$V_{OH}$	Output HIGH Voltage	$V_{CC} = \text{Min.}, I_{OH} = -100\mu\text{A}$	$V_{CC} - 0.2$	—	—	
		$V_{CC} = \text{Min.}, I_{OH} = -8\text{mA}$	2.4	—	—	
$V_{OL}$	Output LOW Voltage QS53806	$V_{CC} = \text{Min.}, I_{OL} = 100\mu\text{A}$	—	—	0.2	
		$V_{CC} = \text{Min.}, I_{OL} = 16\text{mA}$	—	—	0.4	
		$V_{CC} = \text{Min.}, I_{OL} = 24\text{mA}$	—	—	0.5	
$V_{OL}$	Output LOW Voltage QS532806	$V_{CC} = \text{Min.}, I_{OL} = 100\mu\text{A}$	—	—	0.2	
		$V_{CC} = \text{Min.}, I_{OL} = 6\text{mA}$	—	—	0.4	
		$V_{CC} = \text{Min.}, I_{OL} = 8\text{mA}$	—	—	0.5	
$ I_{IN} $	Input Leakage Current	$V_{CC} = \text{Max.}, V_{IN} = 5.5\text{V}, V_{IN} = 0\text{V}$	—	—	1	$\mu\text{A}$
$ I_{OZ} $	Output Leakage Current	$V_{CC} = \text{Max.}, V_{OUT} = 5.5\text{V}, V_{OUT} = 0\text{V}$	—	—	1	
$I_{ODH}$	Output HIGH Current <sup>(2)</sup>	$V_{CC} = 3.3\text{V}, V_{IN} = V_{IH}$ or $V_{IL},$ $V_O = 1.5\text{V}$	-30	-100	-200	mA
$I_{ODL}$	Output LOW Current <sup>(2)</sup>	$V_{CC} = 3.3\text{V}, V_{IN} = V_{IH}$ or $V_{IL},$ $V_O = 1.5\text{V}$	30	100	200	
$I_{OS}$	Short Circuit Current <sup>(2,3)</sup>	$V_{CC} = \text{Max.}, V_{OUT} = \text{GND}$	-60	—	—	mA
$R_{OUT}$	Output Resistance <sup>(4)</sup> QS532806	$V_{CC} = \text{Min}$	—	28	—	$\Omega$

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**Notes:**

1. Typical values indicate  $V_{CC} = 3.3\text{V}$  and  $T_A = 25^{\circ}\text{C}$ .
2. Not more than one output should be used to test this high power condition, and the duration is  $\leq 1$  second.
3. Guaranteed by design but not tested.
4. Output resistance represents the total output impedance of the logic device and includes added series termination resistance.

**Table 5. Power Supply Characteristics**

Symbol	Parameter	Test Conditions <sup>(1)</sup>	Typ <sup>(3)</sup>	Max	Unit	
$I_{CC}$	Quiescent Power Supply Current	$V_{CC} = \text{Max.}, V_{IN} = \text{GND or } V_{CC}$	0.01	100	$\mu\text{A}$	
$\Delta I_{CC}$	Supply Current per Input HIGH	$V_{CC} = \text{Max.}, V_{IN} = 3.0\text{V}$	0.1	30	$\mu\text{A}$	
$I_{CCD}$	Dynamic Power Supply Current Per Output <sup>(2)</sup>	$V_{CC} = \text{Max.}, \overline{\text{OEA}} = \overline{\text{OEB}} = \text{GND}$ Outputs toggling @ 50% duty cycle	40	85	$\mu\text{A}/\text{MHz}$	
$I_C$	Total Power Supply <sup>(2,4)</sup> Current Examples	$V_{CC} = \text{Max.},$ $\overline{\text{OEA}} = \overline{\text{OEB}} = \text{GND}$ 50% duty cycle, $f_1 = 10\text{MHz}$ 5 outputs	$V_{IN} = V_{CC}$ or $V_{IN} = \text{GND}$	2		mA
			$V_{IN} = 3.0\text{V}$ or $V_{IN} = \text{GND}$			
		$V_{CC} = \text{Max.},$ $\overline{\text{OEA}} = \overline{\text{OEB}} = \text{GND}$ 50% duty cycle, $f_1 = 2.5\text{MHz}$ All outputs toggling	$V_{IN} = V_{CC}$ or $V_{IN} = \text{GND}$	1		
			$V_{IN} = 3.0\text{V}$ or $V_{IN} = \text{GND}$			

**Notes:**

- For conditions shown as Min. or Max., use the appropriate values specified under DC specifications.
- Guaranteed but not tested.  $C_L = 0\text{pF}$ .
- Typical values are for reference only. Conditions are  $V_{CC} = 3.3\text{V}$  and  $T_A = 25^\circ\text{C}$ .
- $I_C = I_{CC} + (\Delta I_{CC})(D_H)(N_T) + I_{CCD}(f_O)(N_O)$   
where:  
 $D_H$  = Input duty cycle  
 $N_T$  = Number of TTL HIGH inputs at  $D_H$  (one or two)  
 $f_O$  = Output Frequency  
 $N_O$  = Number of outputs at  $f_O$  (five or ten)

**Table 6. Skew Characteristics Over Operating Range**

Industrial:  $T_A = -40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ ,  $V_{CC} = 3.3 \pm 0.3\text{V}$   
 For QS53806,  $C_{LOAD} = 50\text{pF}$ ,  $R_{LOAD} = 500\Omega$   
 For QS532806,  $C_{LOAD} = 50\text{pF}$  (no resistor)

Symbol	Description <sup>(1,2)</sup>	—		A		B		C		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
$t_{SK(O1)}$	Skew between all outputs same transition, same bank	—	0.5	—	0.35	—	0.3	—	0.3	ns
$t_{SK(O2)}$	Skew between two outputs same transition, different banks	—	0.7	—	0.5	—	0.5	—	0.5	ns
$t_{SK(P)}$	Pulse Skew: Skew between opposite transitions of the same output ( $t_{PHL} - t_{PLH}$ )	—	1.0	—	0.7	—	0.5	—	0.5	ns
$t_{SK(T)}$	Part to part skew <sup>(3)</sup>	—	1.5	—	1.0	—	1.0	—	0.8	ns

**Notes:**

1. Skew parameters are guaranteed but not production tested. Skew parameters apply to propagation delays only.
2. See Test Circuit and Waveforms.
3.  $t_{SK(T)}$  only applies to devices of the same transition, part type, temperature, power supply voltage, loading, package and speed grade.

**Table 7. Switching Characteristics Over Operating Range**

Industrial:  $T_A = -40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ ,  $V_{CC} = 3.3 \pm 0.3\text{V}$   
 For QS53806,  $C_{LOAD} = 50\text{pF}$ ,  $R_{LOAD} = 500\Omega$   
 For QS532806,  $C_{LOAD} = 50\text{pF}$  (no resistor)

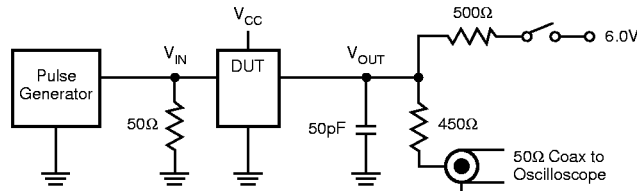
Symbol	Description <sup>(1,2)</sup>	—		A		B		C		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
$t_{PLH}$ $t_{PHL}$	Propagation Delay <sup>(2)</sup>	1.5	6.5	1.5	5.8	1.5	5.0	1.5	4.5	ns
$t_R$	Output Rise Time, 0.8V to 2.0V <sup>(3)</sup>	—	2.0	—	2.0	—	2.0	—	2.0	ns
$t_F$	Output Fall Time, 2.0V to 0.8V <sup>(3)</sup>	—	2.0	—	2.0	—	2.0	—	2.0	ns
$t_{PZL}$ $t_{PZH}$	Output Enable Time	1.5	8.0	1.5	8.0	1.5	6.5	1.5	6.2	ns
$t_{PLZ}$ $t_{PZH}$	Output Disable Time <sup>(3)</sup>	1.5	7.0	1.5	7.0	1.5	6.0	1.5	5.0	ns

**Notes:**

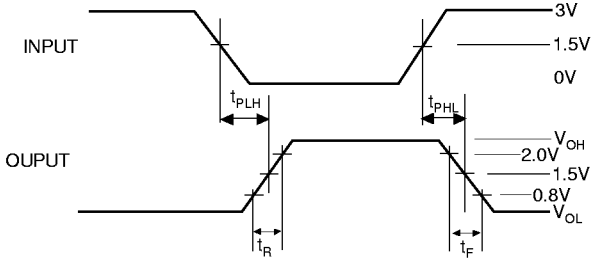
1. See Test Circuit and Waveforms. Minimums guaranteed but not tested.
2. The propagation delay range indicated by Min. and Max. specifications results from process and environmental variables. These propagation delay limits do not imply skew.
3. This parameter is guaranteed by design but not tested.

Figure 3. Test Circuits and Waveforms

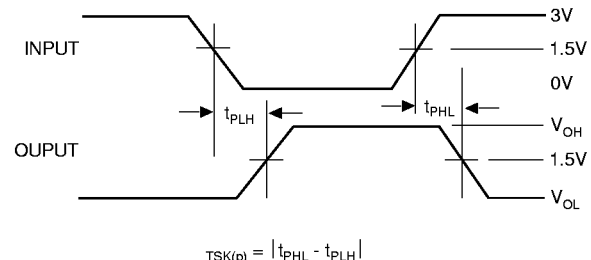
Parameter Tested	Switch Position
$t_{PLZ}, t_{PZL}$	Closed
All Others	Open



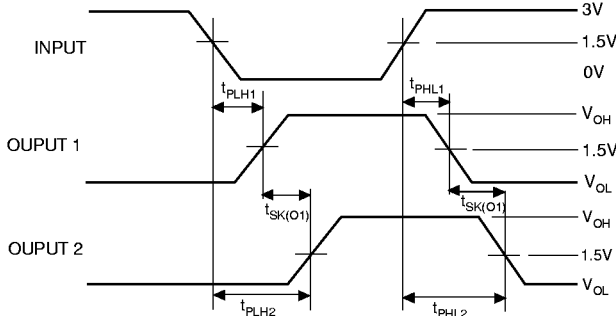
Pulse generator for all pulses:  $f \leq 1.0\text{MHz}$ ;  $t_f \leq 2.5\text{ns}$ ;  $t_r \leq 2.5\text{ns}$



Propagation Delay

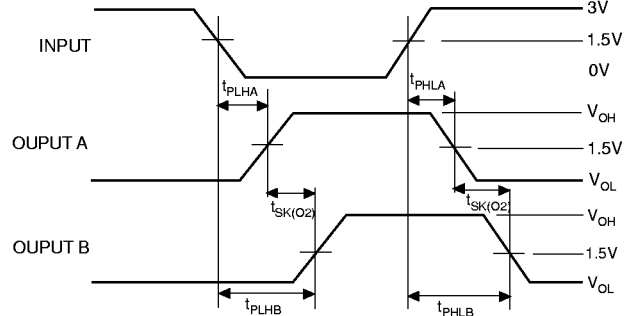


Pulse Skew -  $t_{SK(p)}$



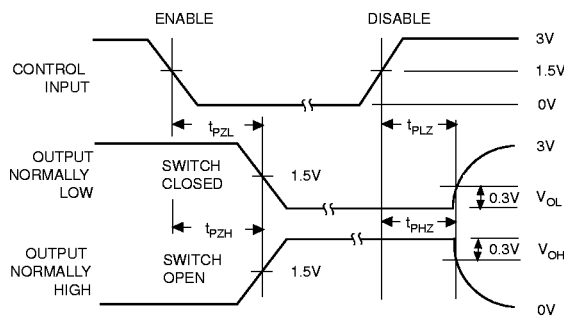
$$t_{SK(O1)} = |t_{PLH2} - t_{PLH1}| \text{ or } |t_{PHL2} - t_{PHL1}|$$

Output Skew (Same Bank) -  $t_{SK(O1)}$

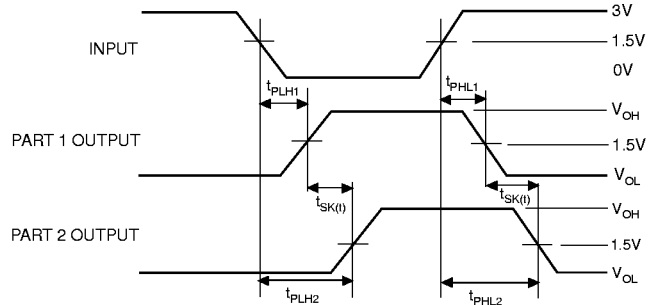


$$t_{SK(O2)} = |t_{PLHB} - t_{PLHA}| \text{ or } |t_{PHLB} - t_{PHLA}|$$

Output Skew (Different Banks) -  $t_{SK(O2)}$



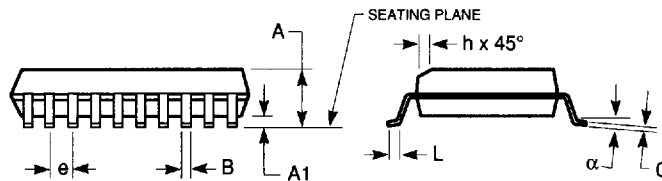
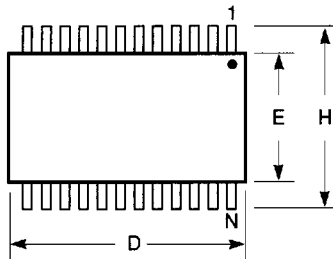
Enable and Disable Times



$$t_{SK(I)} = |t_{PLH2} - t_{PLH1}| \text{ or } |t_{PHL2} - t_{PHL1}|$$

Part-to-Part Skew -  $t_{SK(I)}$

**300-MIL SOIC - Package Code SO**  
Plastic Small Outline Gull-Wing



**Notes:**

1. Refer to applicable symbol list.
2. All dimensions are in inches.
3. N is the number of lead positions.
4. Dimensions D and E are to be measured at maximum material condition but do not include mold flash. Allowable mold flash is 0.006in. per side.
5. Lead coplanarity is 0.004in. maximum.

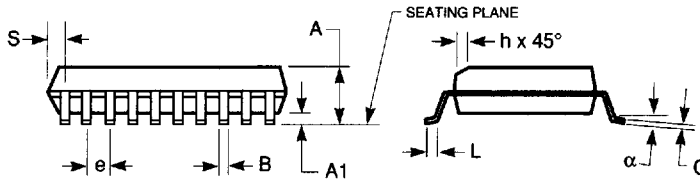
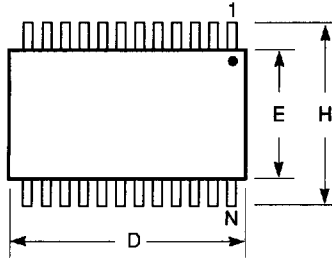
JEDEC#	MS-013AA		MS-013AC		MS-013AD		MS-013AE	
DWG#	PS16A		PS20A		PS24A		PS28A	
Symbol	Min	Max	Min	Max	Min	Max	Min	Max
A	0.096	0.104	0.096	0.104	0.096	0.104	0.096	0.104
A1	0.005	0.011	0.005	0.011	0.005	0.011	0.005	0.011
B	0.014	0.019	0.014	0.019	0.014	0.019	0.014	0.019
C	0.009	0.012	0.009	0.012	0.009	0.012	0.009	0.012
D	0.402	0.412	0.500	0.510	0.602	0.612	0.701	0.711
E	0.292	0.299	0.292	0.299	0.292	0.299	0.292	0.299
e	0.044	0.056	0.044	0.056	0.044	0.056	0.044	0.056
H	0.396	0.416	0.396	0.416	0.396	0.416	0.396	0.416
h	0.010	0.016	0.010	0.016	0.010	0.016	0.010	0.016
L	0.020	0.040	0.020	0.040	0.020	0.040	0.020	0.040
N	16		20		24		28	
$\alpha$	0°	8°	0°	8°	0°	8°	0°	8°

7466803 0003749 900

QUALITY SEMICONDUCTOR, INC.

**150-MIL QSOP - Package Code Q**

**Quarter-Size Outline Package  
Plastic Small Outline Gull-Wing**



**Notes:**

1. Refer to applicable symbol list.
2. All dimensions are in inches.
3. N is the number of lead positions.
4. Dimensions D and E are to be measured at maximum material condition but do not include mold flash. Allowable mold flash is 0.006in. per side.
5. Lead coplanarity is 0.004in. maximum.

JEDEC#	MO-137AB			MO-137AD			MO-137AE			MO-137AF		
DWG#	PSS-16A			PSS-20A			PSS-24A			PSS-28A		
Symbol	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
A	0.060	0.064	0.068	0.060	0.064	0.068	0.060	0.064	0.068	0.060	0.064	0.068
A1	0.004	0.006	0.008	0.004	0.006	0.008	0.004	0.006	0.008	0.004	0.006	0.008
B	0.009	0.010	0.012	0.009	0.010	0.012	0.009	0.010	0.012	0.009	0.010	0.012
C	0.007	0.008	0.010	0.007	0.008	0.010	0.007	0.008	0.010	0.007	0.008	0.010
D	0.189	0.193	0.197	0.337	0.341	0.344	0.337	0.341	0.344	0.386	0.390	0.394
E	0.150	0.154	0.157	0.150	0.154	0.157	0.150	0.154	0.157	0.150	0.154	0.157
e	0.025 BSC			0.025 BSC			0.025 BSC			0.025 BSC		
H	0.230	0.236	0.244	0.230	0.236	0.244	0.230	0.236	0.244	0.230	0.236	0.244
h	0.010	0.013	0.016	0.010	0.013	0.016	0.010	0.013	0.016	0.010	0.013	0.016
L	0.016	0.025	0.035	0.016	0.025	0.035	0.016	0.025	0.035	0.016	0.025	0.035
N	16			20			24			28		
$\alpha$	0°	5°	8°	0°	5°	8°	0°	5°	8°	0°	5°	8°
S	0.006	0.009	0.010	0.056	0.058	0.060	0.031	0.033	0.035	0.031	0.033	0.035

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QUALITY SEMICONDUCTOR, INC.